

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

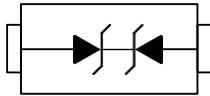


PLED

Product data sheet



SOD-923



### Feature

- 80W peak pulse power per line ( $t_P = 8/20\mu s$ )
- SOD-923 package
- Replacement for MLV(0402)
- Bidirectional configurations
- Response time is typically  $< 1ns$
- Low clamping voltage
- RoHS compliant
- Transient protection for data lines to  
EC61000-4-2(ESD)  $\pm 30KV(air)$ ,  $\pm 30KV(contact)$  ;  
IEC61000-4-4 (EFT) 40A (5/50ns)

### Applications

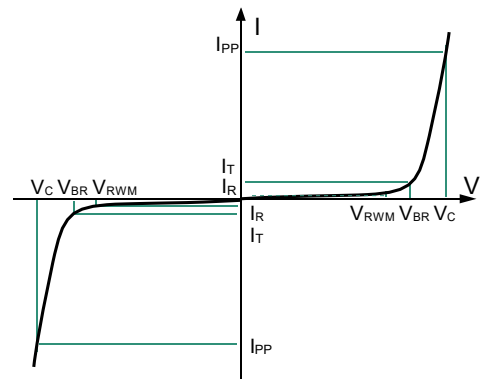
- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

### Mechanical Characteristics

- Lead finish: 100% matte Sn(Tin)
- Mounting position: Any
- Qualified max reflow temperature:  $260^\circ C$
- Device meets MSL 1 requirements
- Pure tin plating:  $7 \sim 17 \mu m$
- Pin flatness:  $\leq 3mil$

### Electronics Parameter

Symbol	Parameter
$V_{RWM}$	Peak Reverse Working Voltage
$I_R$	Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$P_{PP}$	Peak Pulse Power
$C_J$	Junction Capacitance
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$



**Electrical characteristics per line@25°C (unless otherwise specified)**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Peak Reverse Working Voltage	$V_{RWM}$				5	V
Breakdown Voltage	$V_{BR}$	$I_t = 1mA$	5.6	6.7	7.8	V
Reverse Leakage Current	$I_R$	$V_{RWM} = 5V T=25^\circ C$			1.0	$\mu A$
Maximum Reverse Peak Pulse Current	$I_{PP}$			5		A
Clamping Voltage	$V_C$	$I_{PP}=1A$			8	V
Clamping Voltage	$V_C$	$I_{PP}=3A$			13	V
Clamping Voltage	$V_C$	$I_{PP}=5A$			15	V
Junction Capacitance	$C_j$	$V_R=0V f = 1MHz$		12	15	pF

**Absolute maximum rating@25°C**

Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p=8/20\mu s$ )	$P_{pp}$	80	W
Operating Temperature	$T_J$	-55 to +150	$^\circ C$
Storage Temperature	$T_{STG}$	-55 to +150	$^\circ C$

**Typical Characteristics**

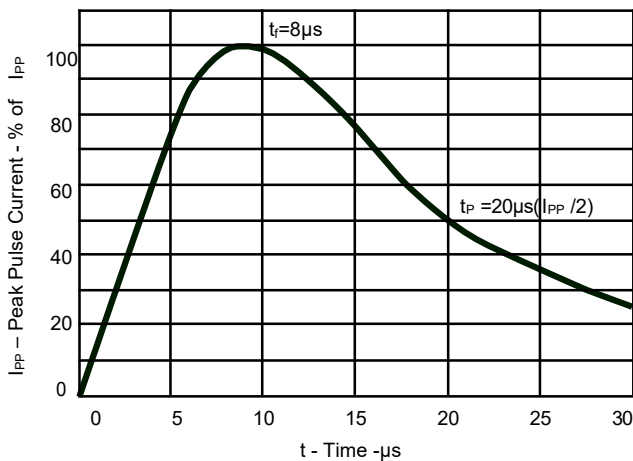


Fig 1.Pulse Waveform

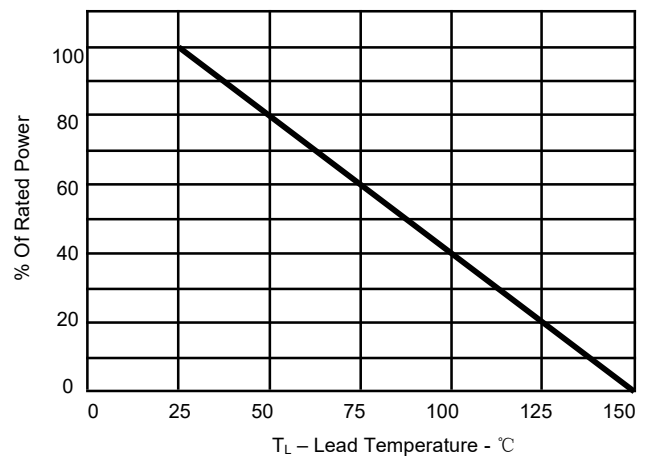


Fig 2.Power Derating Curve

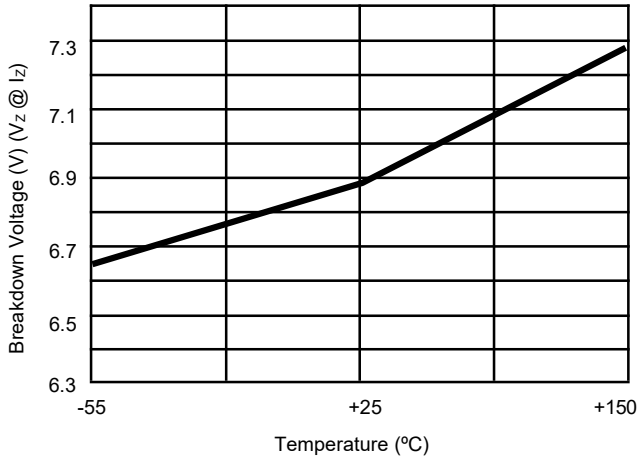


Fig 3. Typical Breakdown Voltage vs. Temperature

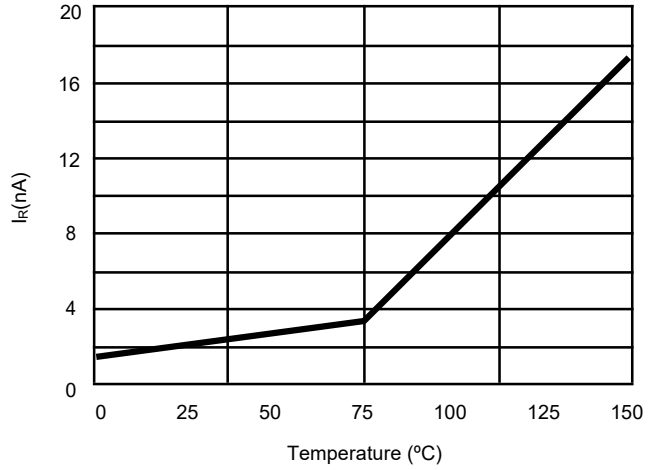


Fig 4. Typical Leakage Current vs. Temperature

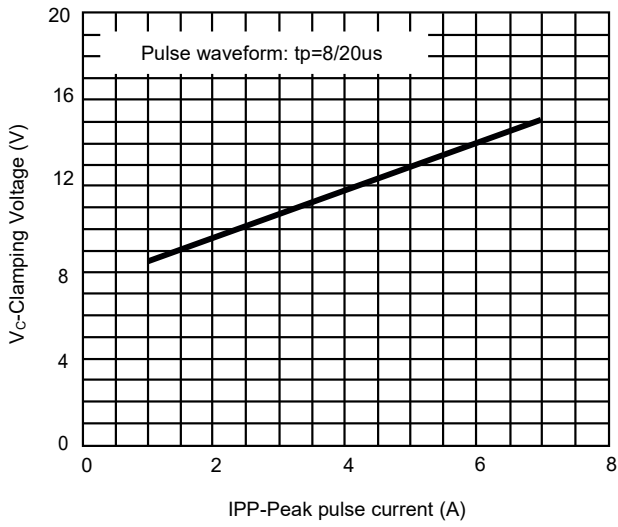


Fig 5. Clamping voltage vs. Peak pulse current

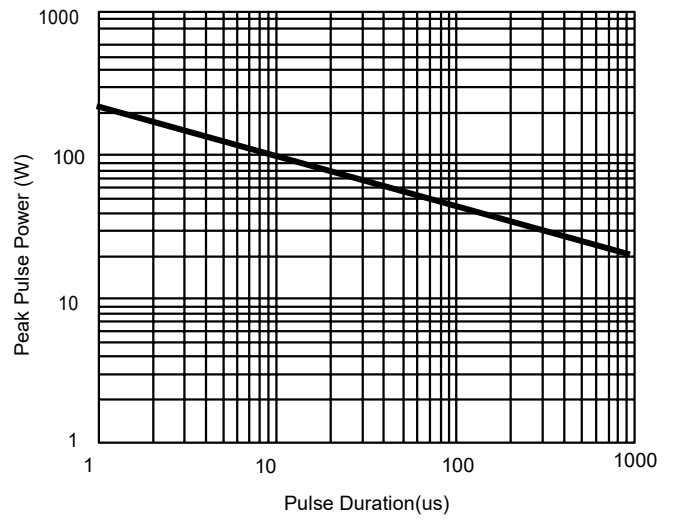
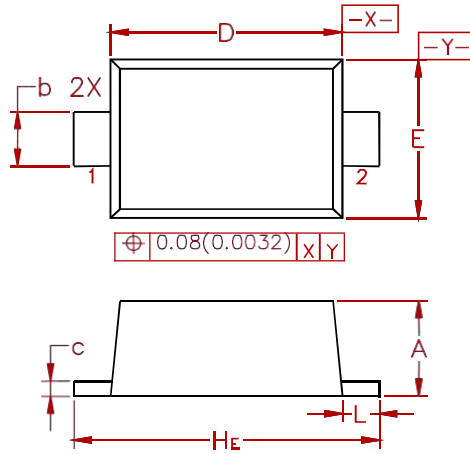


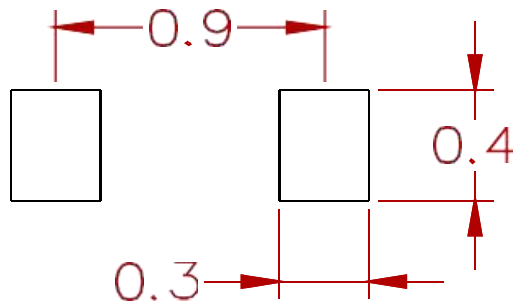
Fig 6. Non-Repetitive Peak Pulse Power vs. Pulse time

**PACKAGE MECHANICAL DATA**



Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.36	0.40	0.43	0.014	0.016	0.017
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

**Suggested Pad Layout**



Dimensions: Millimeters

**REEL SPECIFICATION**

P/N	PKG	QTY
ESD9B5.0ST5G	SOD-923	8000

## Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringement of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.